

## SCOPE OF CONFERENCE

JSME and ASME jointly hold the second international conference on engineering materials and materials processing technology, organized by the Materials and Processing Division of JSME, along with the Manufacturing Engineering, the Materials, the Applied Mechanics and the Tribology Divisions of ASME. This is also held as the thirteenth annual JSME Materials and Processing Conference and is recognized as the premier meeting on materials and processing technology in Japan. JSME/ASME International Conference on Materials and Processing 2005 (M&P2005) will be held at Crowne Plaza Hotel - Seattle, Seattle, USA on June 19 through 22, 2005. The M&P2005 will provide an up-to-date scientific and technical conference covering broad areas of interest on engineering materials and processing.

## TECHNICAL TOPICS

### Group A: Material and Processing

- (A-1) Polymers and Polymer Matrix Composites
- (A-2) Metals and Metal Matrix Composites
- (A-3) Ceramics, Ceramic Matrix Composites, and C/C Composites
- (A-4) Plastic Forming and Advanced Products
- (A-5) Casting
- (A-6) Advanced Powder Processing Technique
- (A-7) Advanced Welding and Bonding Techniques
- (A-8) Coating and Thermal Spray
- (A-9) Ultra-Precision and Micro Forming of Materials
- (A-10) High Energy Forming
- (A-11) Superplastic Forming
- (A-12) Mechanical Processing

### Group B: Properties and Applications

- (B-1) Mechanical Characterization and Measurement Techniques
- (B-2) Intelligent Systems for Material Process and Inspection
- (B-3) Adhesion and Interfaces
- (B-4) Contact Surface Mechanics and Fracture
- (B-5) Surface Modification Techniques, Wear, and Tribology
- (B-6) Smart Materials and Structures
- (B-7) Impact Behavior of Materials and Structures

(B-8) Non-destructive Inspection Techniques

(B-9) Other Properties and Applications

## REGISTRATION FEE

Registration Fee:	before February 28	after February 28
(JSME/ASME Member)	¥55,000	¥60,000
(Non-member)	¥65,000	¥70,000
Student	¥35,000	¥40,000

The registration fee includes admittance to all the conferences, a copy of the abstracts, a CD-ROM of proceedings, coffee breaks, lunches, reception (June 19), and banquet (June 21).

## PRESENTATION

Both oral and poster presentations are acceptable. The oral presentation consists of 15 minutes presentation and 5 minutes discussion. Presenters are requested to provide the preference on the mode of presentation (oral, poster, oral or poster).

## SUBMISSION OF ABSTRACT

Authors should submit 250-word text only abstract, **no later than October 15, 2004** through the conference website ([Japanese version, http://www.jsme.or.jp/mpd/IM&P2005.htm](http://www.jsme.or.jp/mpd/IM&P2005.htm)), ([English version, http://www.jsme.or.jp/mpd/IM&P2005-e.htm](http://www.jsme.or.jp/mpd/IM&P2005-e.htm)) including 1) paper title, 2) authors' names, 3) affiliation, 4) job title, 5) mailing address, 6) phone and fax, and 7) E-mail address. The authors should also select the mode of presentation (oral, poster, oral or poster) and show preference for submission to JSME Int. J. special issue or Trans. ASME only if you wish.

## PREPARATION OF PROCEEDING PAPERS

Authors accepted to present in M&P2005 should prepare papers for the proceedings. The proceeding paper must be written in English and should not exceed 6 pages including text, figures, tables and references regardless the mode of presentation. The typing must be on 21 cm x 29.7 cm (A4-size) white bond paper on

one side only within a frame of 17 cm x 24 cm. Electronic submission is planned. Details will be available on the website of this conference. Authors should send their manuscript **no later than January 14, 2005**.

## SPECIAL ISSUE

A special issue on engineering material and processing of the International Journal of JSME (only at most 35 selected papers) is scheduled for publication. Authors are encouraged to submit original papers to the special issue. Authors who would like to submit to the transactions of ASME are also encouraged. Details will be available on the website of this conference.

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#### Hotel Information

Conference official hotel: Crowne Plaza Hotel- Seattle  
 (<http://www.crowneplazaseattle.com>)  
 The hotel has reserved a limited block of rooms at a reduced rate for conference attendees. See details in our website.

# Second Circular

## 2<sup>nd</sup> JSME/ASME International Conference on Materials and Processing 2005

13<sup>th</sup> JSME Materials and Processing Conference (M&P2005)

**June 19 - 22, 2005**

**Crowne Plaza Hotel - Seattle**  
Seattle, Washington, USA

<http://www.jsme.or.jp/mpd/IM&P2005.htm>  
<http://www.jsme.or.jp/mpd/IM&P2005-e.htm>

#### KEY SCHEDULE and DEADLINES

The 250-word text only abstract in English should be submitted no later than October 15, 2004.

Acceptance notification: October 29, 2004

Paper submission for proceedings: January 14, 2005

Final program delivery: March 31, 2005

Organized by  
the Japan Society of Mechanical Engineers (JSME) and the  
American Society of Mechanical Engineers (ASME)

